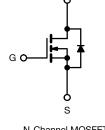
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Power MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	600				
R _{DS(on)} (Ω)	V _{GS} = 10 V 1.2				
Q _g max. (nC)	42				
Q _{gs} (nC)	10				
Q _{gd} (nC)	20				
Configuration	Single				

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N-Channel MOSFET

FEATURES

 Low gate charge Q_g results in simple drive Requirement



- Improved gate, avalanche and dynamic dV/dt RoHS* ruggedness
- Fully characterized capacitance and avalanche voltage and current
- Effective Coss specified
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

Note

This datasheet provides information about parts that are RoHS-compliant and / or parts that are non-RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details.

APPLICATIONS

- Switch mode power supply (SMPS)
- Uninterruptible power supply
- · High speed power switching

TYPICAL SMPS TOPOLOGIES

Single transistor forward

ORDERING INFORMATION			
Package	TO-220AB		
Lead (Pb)-free	IRFBC40APbF		
	SiHFBC40A-E3		
SnPb	IRFBC40A		
	SiHFBC40A		

ABSOLUTE MAXIMUM RATINGS ($T_C = 25 \degree C$, unless otherwise noted)					
PARAMETER			SYMBOL	LIMIT	UNIT
Drain-Source Voltage			V _{DS}	600	V
Gate-Source Voltage			V _{GS}	± 30	- V
Continuous Drain Current	V _{GS} at 10 V	T _C = 25 °C	la la	6.2	
Continuous Drain Current	v _{GS} at 10 v	T _C = 100 °C	ID	3.9	А
Pulsed Drain Current ^a			I _{DM}	25	
Linear Derating Factor				1.0	W/°C
Single Pulse Avalanche Energy ^b			E _{AS}	570	mJ
Repetitive Avalanche Current ^a			I _{AR}	6.2	А
Repetitive Avalanche Energy ^a			E _{AR}	13	mJ
Maximum Power Dissipation $T_{C} = 25 \text{ °C}$			PD	125	W
Peak Diode Recovery dV/dt ^c			dV/dt	6.0	V/ns
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +150	°C
Soldering Recommendations (Peak temperature) ^d for 10 s				300	
Mounting Torque	6.20 or 1	C 00 au M0 a august		10	lbf ∙ in
Mounting Torque	6-32 or M3 screw			1.1	N · m

Notes

Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11). Starting T_J = 25 °C, L = 29.6 mH, R_g = 25 Ω , I_{AS} = 6.2 A (see fig. 12). I_{SD} \leq 6.2 Å, dl/dt \leq 80 A/µs, V_{DD} \leq V_{DS}, T_J \leq 150 °C. a.

b.

c.

d. 1.6 mm from case.

S16-0763-Rev. D, 02-May-16



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THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R _{thJA}	-	62	
Case-to-Sink, Flat, Greased Surface	R _{thCS}	0.50	-	°C/W
Maximum Junction-to-Case (Drain)	R _{thJC}	-	1.0	

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static		*			•	•	
Drain-Source Breakdown Voltage	V _{DS}	V _{GS}	= 0 V, I _D = 250 μA	600	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	ce to 25 °C, I _D = 1 mA	-	0.66	-	V/°C
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	2.0	-	4.0	V
Gate-Source Leakage	I _{GSS}		V _{GS} = ± 30 V	-	-	± 100	nA
Zaus Osta Valta za Dusia Orumant		V _{DS} =	V _{DS} = 600 V, V _{GS} = 0 V		-	25	•
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 480 V	/, V _{GS} = 0 V, T _J = 125 °C	-	-	250	μA
Drain-Source On-State Resistance	R _{DS(on)}	$V_{GS} = 10 V$	I _D = 3.7 A ^b	-	-	1.2	Ω
Forward Transconductance	9 _{fs}	V _{DS}	= 50 V, I _D = 3.7 A	3.4	-	-	S
Dynamic					•	•	
Input Capacitance	C _{iss}		V _{GS} = 0 V,	-	1036	-	
Output Capacitance	C _{oss}		$V_{DS} = 25 V,$	-	136	-	
Reverse Transfer Capacitance	C _{rss}	f = 1	.0 MHz, see fig. 5	-	7.0	-	
	C _{oss}	V _{GS} = 0 V	V _{DS} = 1.0 V, f = 1.0 MHz	-	1487	-	- pF
Output Capacitance			V _{DS} = 480 V, f = 1.0 MHz	-	36	-	
Effective Output Capacitance	Coss eff.		V_{DS} = 0 V to 480 V ^c	-	48	-	
Total Gate Charge	Qg			-	-	42	
Gate-Source Charge	Q _{gs}	$V_{GS} = 10 V$ $I_D = 6.2 A, V_{DS} = 480 V$ see fig. 6 and 13 ^b		-	-	10	nC
Gate-Drain Charge	Q _{gd}		see lig. 6 and 13 ~		-	20	
Turn-On Delay Time	t _{d(on)}			-	13	-	- ns
Rise Time	t _r		V _{DD} = 300 V, I _D = 6.2 A		23	-	
Turn-Off Delay Time	t _{d(off)}	$R_g = 9.1 \ \Omega, R_D = 47 \ \Omega,$ see fig. 10 ^b		-	31	-	
Fall Time	t _f		see lig. 10 ⁻²	-	18	-	1
Gate Input Resistance	Rg	f = 1 MHz, open drain		0.6	-	3.9	Ω
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	6.2	
Pulsed Diode Forward Current ^a	I _{SM}			-	-	25	A
Body Diode Voltage	V _{SD}	T _J = 25 °C, I _S = 6.2 A, V _{GS} = 0 V ^b		-	-	1.5	V
Body Diode Reverse Recovery Time	t _{rr}	$- T_{\rm J} = 25 ^{\circ}\text{C}, I_{\rm F} = 6.2 \text{ A}, \text{dl/dt} = 100 \text{ A/}\mu\text{s}^{\rm b}$		-	431	647	ns
Body Diode Reverse Recovery Charge	Q _{rr}			-	1.8	2.8	μC
Forward Turn-On Time	t _{on}	Intrinsic tu	urn-on time is negligible (turn	-on is dor	ninated b	vleand	<u>.</u> Ln)

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).

b. Pulse width \leq 300 µs; duty cycle \leq 2 %.

c. C_{oss} eff. is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS} .

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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

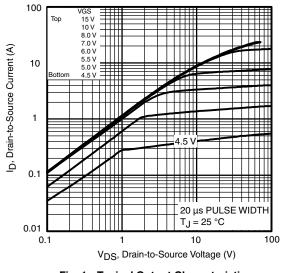


Fig. 1 - Typical Output Characteristics

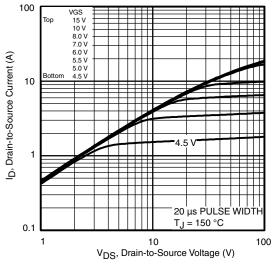


Fig. 2 - Typical Output Characteristics

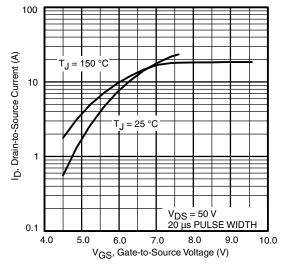


Fig. 3 - Typical Transfer Characteristics

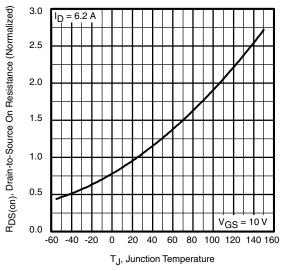


Fig. 4 - Normalized On-Resistance vs. Temperature



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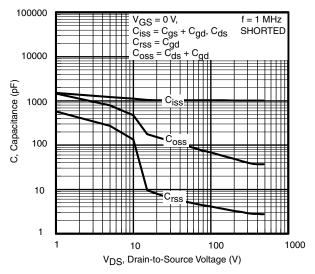


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

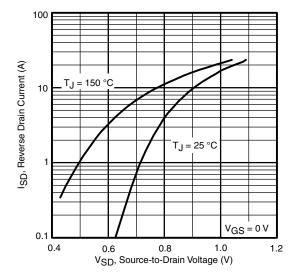


Fig. 7 - Typical Source-Drain Diode Forward Voltage

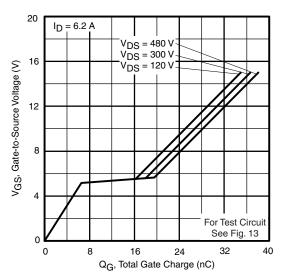


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

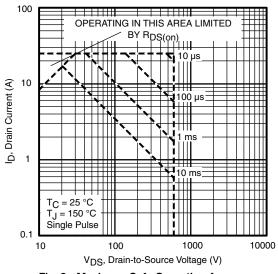


Fig. 8 - Maximum Safe Operating Area



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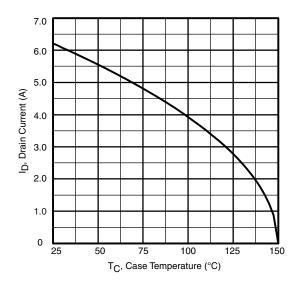


Fig. 9 - Maximum Drain Current vs. Case Temperature

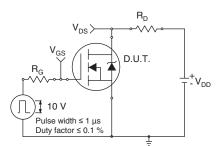


Fig. 10a - Switching Time Test Circuit

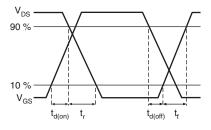


Fig. 10b - Switching Time Waveforms

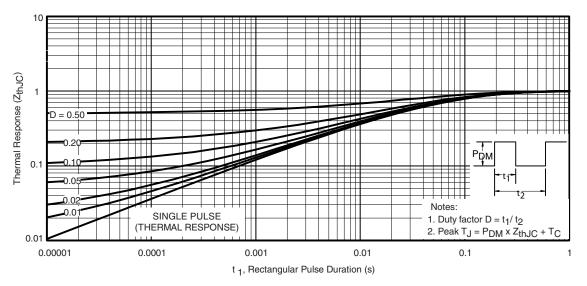


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case



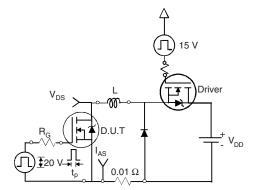


Fig. 12a - Unclamped Inductive Test Circuit

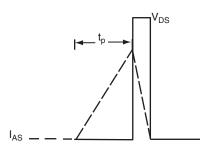


Fig. 12b - Unclamped Inductive Waveforms

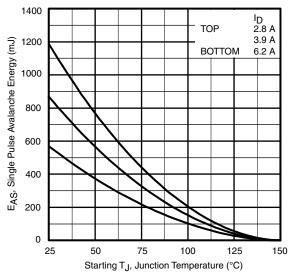


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

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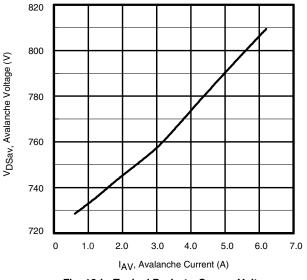


Fig. 12d - Typical Drain-to-Source Voltage vs. Avalanche Current

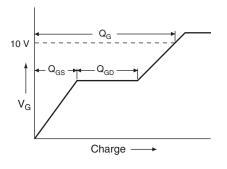


Fig. 13a - Basic Gate Charge Waveform

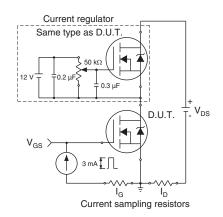
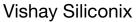


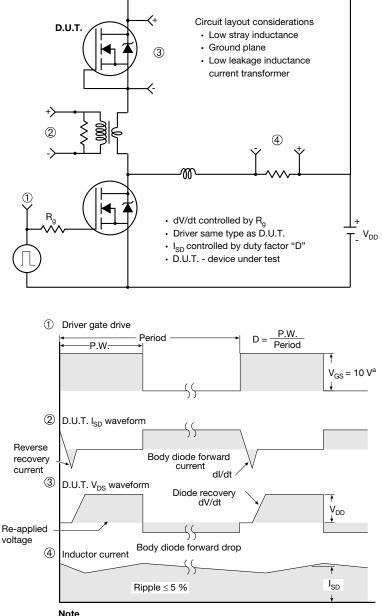
Fig. 13b - Gate Charge Test Circuit

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Peak Diode Recovery dV/dt Test Circuit



a. $V_{GS} = 5$ V for logic level devices

Fig. 14 - For N-Channel

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TO-220-1



DIM.	MILLIN	IETERS	INC	HES
DIN.	MIN.	MAX.	MIN.	MAX.
А	4.24	4.65	0.167	0.183
b	0.69	1.02	0.027	0.040
b(1)	1.14	1.78	0.045	0.070
С	0.36	0.61	0.014	0.024
D	14.33	15.85	0.564	0.624
E	9.96	10.52	0.392	0.414
е	2.41	2.67	0.095	0.105
e(1)	4.88	5.28	0.192	0.208
F	1.14	1.40	0.045	0.055
H(1)	6.10	6.71	0.240	0.264
J(1)	2.41	2.92	0.095	0.115
L	13.36	14.40	0.526	0.567
L(1)	3.33	4.04	0.131	0.159
ØΡ	3.53	3.94	0.139	0.155
Q	2.54	3.00	0.100	0.118
ECN: X15-0364-Rev. C, 14-Dec-15 DWG: 6031				

Note

- M^{\star} = 0.052 inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM

Package Picture				
AS	3E	Xi	'an	
		IRF 9510 744K AB		

Revison: 14-Dec-15

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